

REMARKS

Claims 1-11, 14, 26-28 and 30-38 are pending in this application. Claims 1-5, 7-9, 11, 14, 26-28, 30, 31 and 33-38 are amended herein. Claims 12, 13, 15-25 and 29 were previously canceled. Claims 9 and 10, which were previously withdrawn by the Examiner, are no longer withdrawn. Applicants respectfully request reconsideration of the claims in view of the following remarks.

As an initial matter, Applicants would like to thank the Examiner for allowing claims 7-11, 14 and 34-38. The Examiner also notes previously withdrawn claims 9 and 10 are now allowable.

The Examiner objected to the drawings as not showing every feature of the invention specified in the claims. Applicants have submitted herewith replacement drawing sheets to comply with the Examiner's request.

New figures 4A-4E have been added and the specification has been amended to include corresponding text. No new matter is added. All the amended contents were included in the original disclosure (see, e.g., paragraph [0011]). Applicants request the Examiner to withdraw these objections.

Claims 26 and 33 have been amended in response to the Examiner's objections. Applicants request the Examiner to withdraw these objections.

Claims 26-28, 30 and 32-33 were rejected under 35 U.S.C. § 102(b) as being anticipated by Perng, *et al.* (U.S. Patent No. 6,066,570, hereinafter "Perng").

Claim 26 as currently amended, specifically recites "wherein the material is not disposed on a bottom surface of the wafer." Perng does not teach or suggest that the material is not disposed on the bottom surface. Rather, in Perng the material is disposed on the bottom surface.

For example, see Figure 1, in which element 16 is coated on the front, side and back of the wafer, and also see column 3, lines 26-29. Hence, independent claim 26 is allowable.

Claims 27, 28 and 30-33 depend from claim 26 and add further limitations. It is respectfully submitted that these dependent claims are allowable by reason of depending from an allowable claim as well as for adding new limitations.

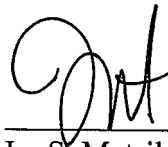
Claims 1-6 were rejected under 35 U.S.C. § 103(a) as being unpatentable over Perng in view of Wolf (Silicon Processing, Vol. 1, hereinafter "Wolf").

Claim 1, as currently amended, specifically recites "wherein the organic material is not present on a bottom surface of the wafer." The disclosure of Perng either singly or in combination with Wolf does not teach or suggest that the material is not disposed on the bottom surface. Rather, in Perng the material is disposed on the bottom surface. For example, see Figure 1, in which element 16 is coated on the front, side and back of the wafer, and see also column 3, lines 26-29. Hence, independent claim 1 is allowable.

Claims 2-6 depend from claim 1 and add further limitations. It is respectfully submitted that these dependent claims are allowable by reason of depending from an allowable claim as well as for adding new limitations.

Applicants have made a diligent effort to place the claims in condition for allowance. However, should there remain unresolved issues that require adverse action, it is respectfully requested that the Examiner telephone Ira S. Matsil, Applicants' attorney, at 972-732-1001, so that such issues may be resolved as expeditiously as possible. No fee is believed due in connection with this filing. However, should one be deemed due, the Commissioner is hereby authorized to charge, or credit any overpayment to, Deposit Account No. 50-1065.

Respectfully submitted,



Ira S. Matsil
Attorney for Applicants
Reg. No. 35,272

11/26/07

Date

Slater & Matsil, L.L.P.
17950 Preston Rd., Suite 1000
Dallas, Texas 75252-5793
Tel.: 972-732-1001
Fax: 972-732-9218